

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Seong Min Seo, Young Suk Chung, Jong Sik Paek, Jae Hun Ku, Jae Hak Yee

Assignee:

Amkor Technology, Inc.

Title:

Semiconductor Package Including Stacked Chips

Serial No.:

09/816,599

Filing Date:

March 23, 2001

Examiner:

Not Yet Assigned

Group Art Unit:

Not Yet Assigned

Docket No.:

AB-1111 US

San Jose, California
April 10, 2001

Attn: Official Draftsperson
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

SUBMISSION OF FORMAL DRAWINGS

Dear Sir:

Applicants submit 3 sheets of formal drawings, consisting of Figures 1, 2A, 2B, 3A, 3B, 4A, 4B, 5A, 5B, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (408) 453-9200.

EXPRESS MAIL LABEL NO:

EL 710 212 729 US

Respectfully submitted,

James E. Parsons
James E. Parsons
Attorney for Applicants
Reg. No. 34,691

LAW OFFICES OF
SKJERVEN MORRILL
MacPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979